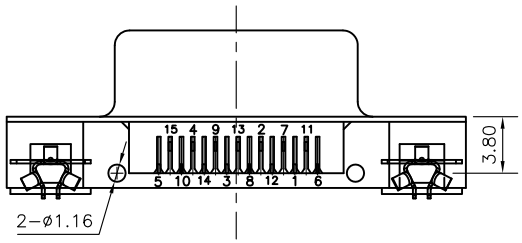
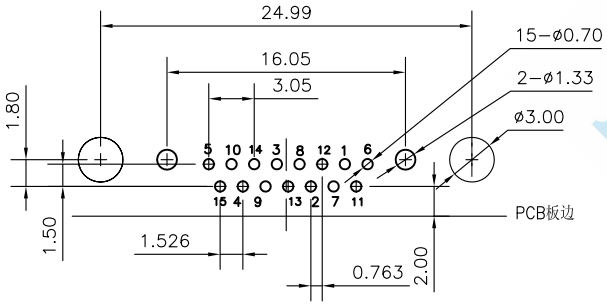
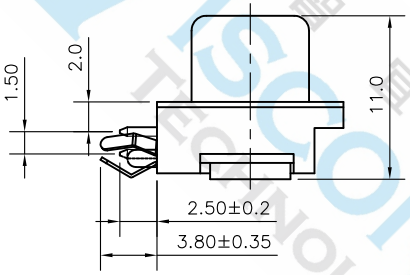
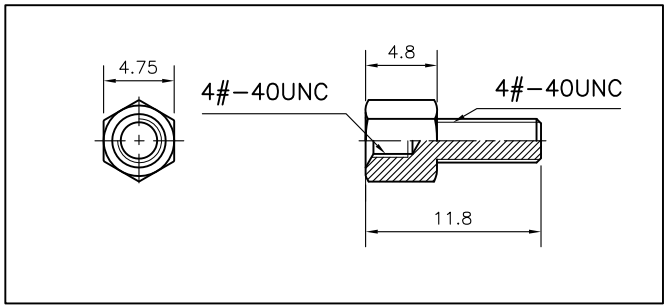
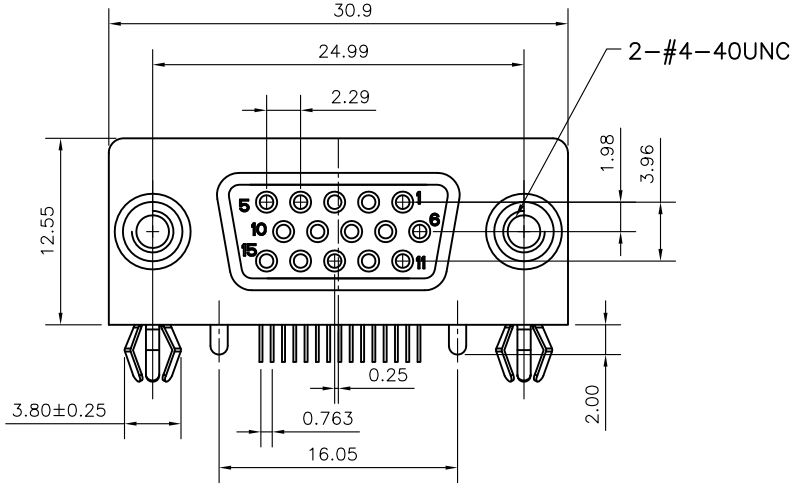




RECOMMENDED P.C.B LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)







1. MATERIAL&PLATING:
   - 1.1 Insulator: PBT+30%G.F, UL94V-0,COLOR: BLUE
   - 1.2 Contact: Copper Alloy(t=0.20),
     Gold Flash Plated In Contact Area,
     80u" Min. Tin Plated In Solder Area,
     30u" Min. Nickel Underplated Overall.
   - 1.3 Shell: Spcc, 50u" Min. Nickel Plated Overall.
   - 1.4 Board Lock: Spcc, 80u" Min. Tin Plated Over
     30u" Min. Nickel Underplated Overall.
   - 1.5 Rivet: Copper alloy, 30u" Min. Nickel Plated Overall.

2. SPECIFICATION:
   - 2.1 Current Rate: 3 Amps
   - 2.2 Insulator Resistance: 1000MΩ Min. at 500V DC
   - 2.3 Dielectric Strength: AC 500V Per minute
   - 2.4 Operation Temperature: -25°C to+85°C

3. NOTES:
   - 3.1 ALL COMPONENTS ARE RoHS COMPLIANT.
   - 3.2 RESISTANCE TO SOLDERING HEAT: 255°C FOR 5 SECONDS, AND ONLY FOR WAVE SOLDERING PROCESS.

WISCONN TECHNOLOGY 威訊科技

DIMENSIONS TOLERANCE METRIC								
Up to 5 ±0.2 Above 5~15 ±0.3 Above 15~30 ±0.4 Above 30~50 ±0.5 Angle ±0.3°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME) DB 15F Slim Type 2.0mm 90度 DIP	WISCONN Technology Co.,Ltd Tel:02-2790-1979 Fax:02-2790-1569
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena	料號(PART NUMBER) WDBF-15-xFxxR14	
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期(DATE)	MAY.25.2016	圖號(DRAW NUMBER) C008 圖檔(FILE NAME .DWG)	比例(SCALE) 1/1 圖紙(SIZE) A4 頁次(SHEET) 1 版次(REV.) A